



AAEON Technology INC.
ISO-9001/ISO-14001 Certified
Industrial Automation PCs

PCM-6890B

Thermal Image Analysis Report

Release Date: JUNE.29, 2000

Issue Stamp

QA Manager

QE Manager

Test Engineer

Thermal Image Analysis

I . Model Name: PCM-6890B

II . Description: FC/Socket 370 Compact Board with LD, Ethernet, Audio, & 4 COMs

III . Date: JUNE. 29, 2000

IV. Measure Site: AAEON QE Dept.

V . Issued by : Fenglin Dong

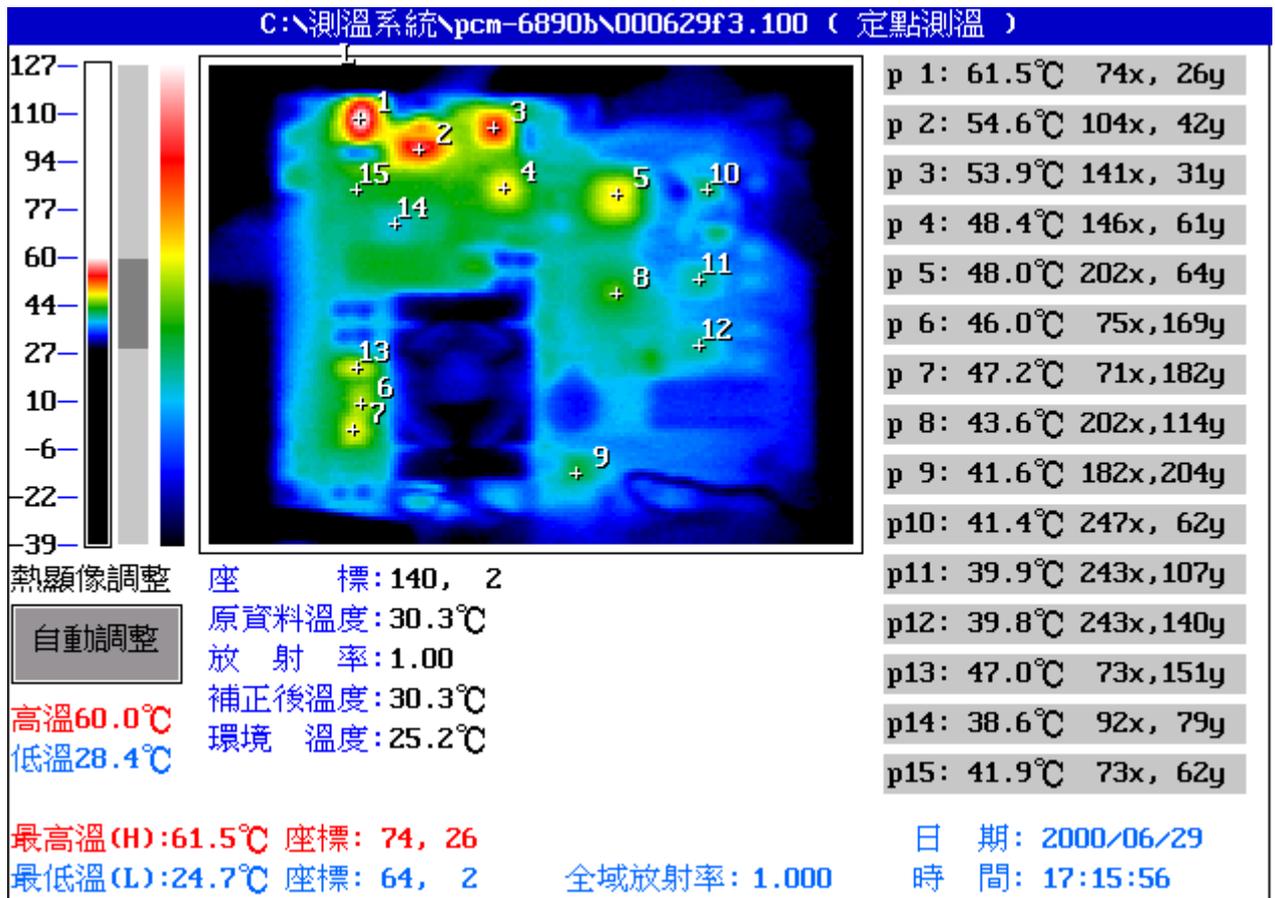
VI.Equipment: TVS-100 series by NIPPON AVIONICS CO., LTD.

VII. Simulation Environment:

- **Temperature: 25.2 degrees C**
- **CPU: Celeron**
- **RAM: 128 MB**
- **Hardware: DiskOnChip**
- **Application Software: QAPLUS/FE V5.2**
- **Take Picture Time: Power on 30 minutes after**

VIII. Prediction Result:

1. Component Side:



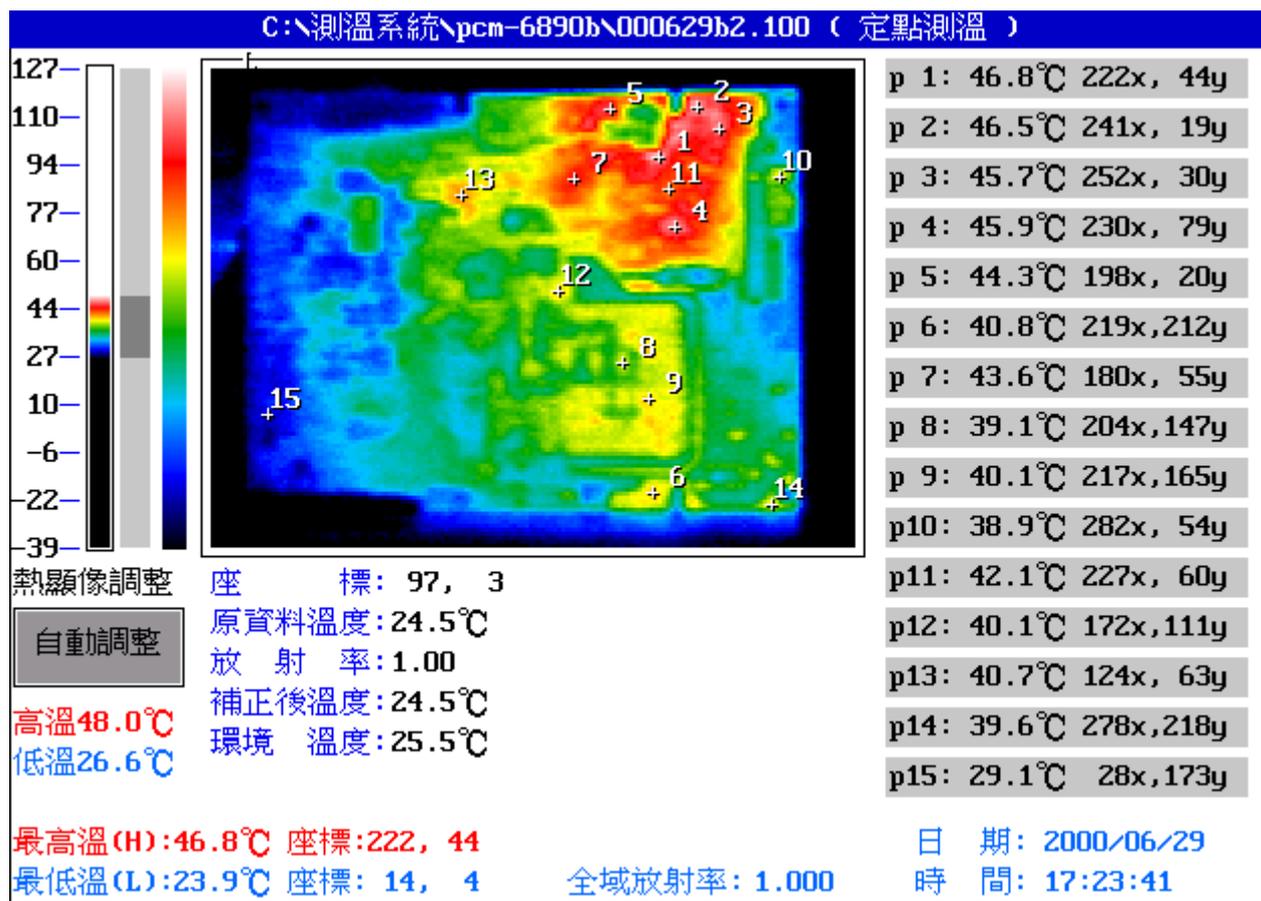
Point	Position	Describe	Ts	Tm	Note
1	U1	ICS-9248-39	70	61.5	※ = -26.5
2	Q4	AMS 1083CT	---	54.6	
3	U4	ESS1938	70	53.9	※ = -18.9
4	U5	INTEL, G082559	75	48.4	※ = -8.4
5	U13	CHIPS, B69000	70	48.0	※ = -13
6	Q2	PHB 50N003LT	---	46.0	
7	Q3	PHB 50N003LT	---	47.2	
8	U14	INTEL, FW82371EB SL37M	75	43.6	※ = -8.6
9	U11	16V8	---	41.6	
10	---				
11	U21	ITE TI8661F	70	39.9	
12	U22	Winbond W83977EF	70	39.8	
13	---				
14	U2	82443BX	70	39.6	
15	U2	82443BX	70	41.9	※ = -6.9

1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)

2. Solder Side:



Point	Position	Describe	Ts	Tm	Note
1	---				
2	---				
3	---				
4	---				
5	---				
6	---				
7	---				
8	---				
9	---				
10	---				
11	---				
12	---				
13	---				
14	---				
15	---				

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